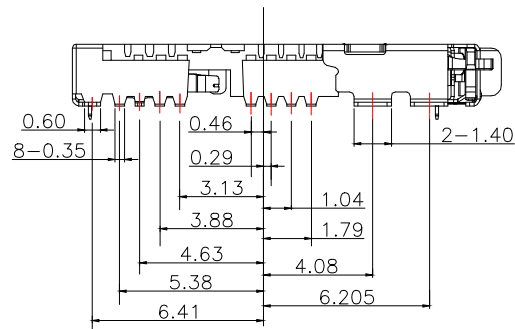
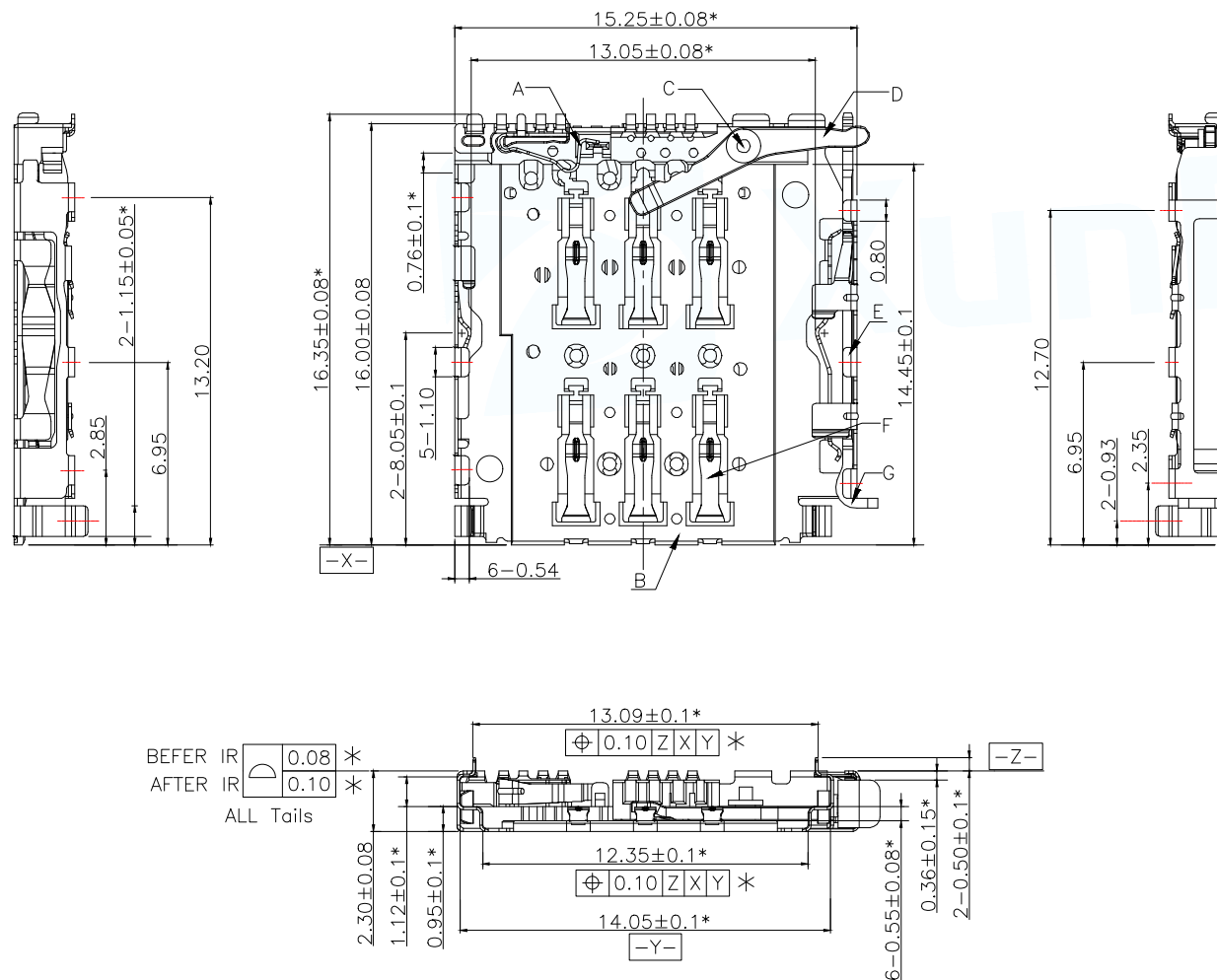




- 1) PRODUCT SPECIFICATIONS:
 - 1-1:VOLTAGE RATING: 10V
 - 1-2:CURRENT RATING: 0.5V
 - 1-3:INSULATION RESISTANCE:
1000 MEG.OHM MIN
 - 1-4:CONTACT RESISTANCE:100mΩ Max:
 - 1-5:OPERATION TEMPERATURE:-40°TO+85°
 - 1-6:DURABILITY: 3000 CYCLES
- 2) DIMENSIONS WITH MARK"*"INDICATE
THE CRITICAL DIMENSIONS



G	Lever	1	SUS301-3/4H	NA
F	Contact	1	C5240HQ-SH	Contact:10u"Min Au,Sloder:2u"Min Au 50~150u Ni underplating over all
E	Shell	1	SUS301-H	Solder:2u"Min Au,50~120u"Ni underplating over all
D	Bar	1	SUS301-H	NA
C	Rivet	1	SUS303-CU 1/2H	NA
B	Housing	1	LCP-S475	100%RAW MATERIAL
A	Switch	1	C7035-XE	Contact:10u" Min Au,Solder:2u" Min Au 50~150u" Ni underplating over all
ITEM	NAME	Q'TY	MATERIAL	PLATING

MANUFACTURE DWG



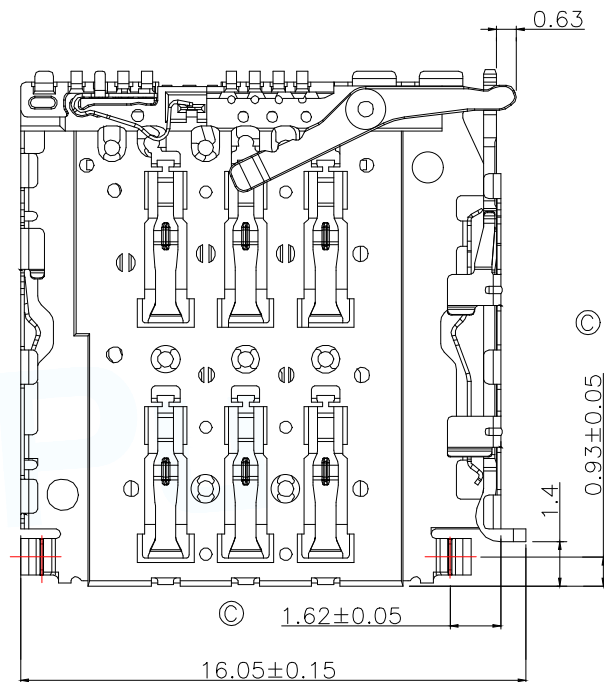
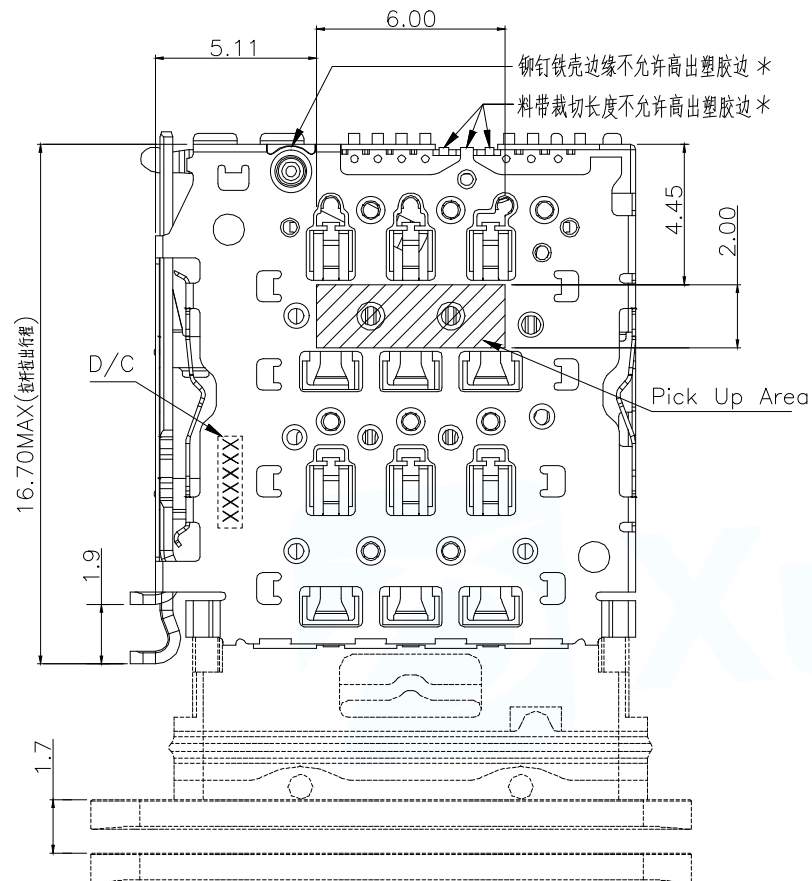
东莞市讯普电子科技有限公司
DongGuan XunPu Electronics Co.,Ltd

UNLESS OTHERWISE
SPECIFIED TOLERANCES



TITLE:2.3H 3 IN 2卡座
FOR CUSTOMER

DECIMALS:	ANGLES:		DWN	EUCAS	
X.:±0.25	X.:±2°		CHKD	Ethan	
X.X:±0.20	X.X':±1°		APVD	Jacob	
X.XX:±0.15			SCALE:1:1	UNIT:MM	
		CUSTOMER COPY	SIZE:A4	SHEET:1F4	REV:A



D/C ANNOTATION

LX XXXXXX

Class(A:Day shift,B:Night shift)

Line(01,02,03...)

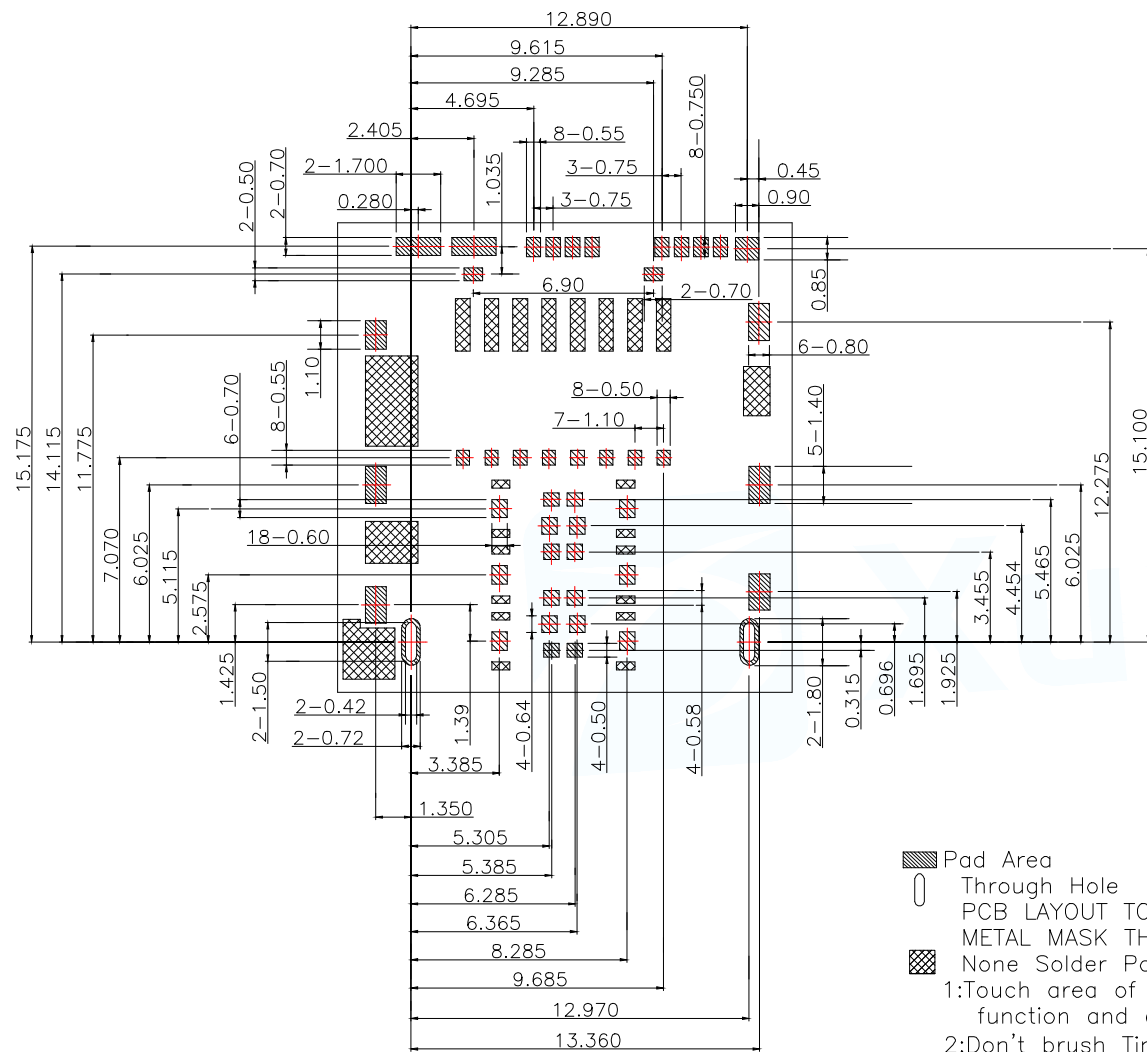
Date(1;2;3..A;B...)

Month(A:Jan; B;Feb...)

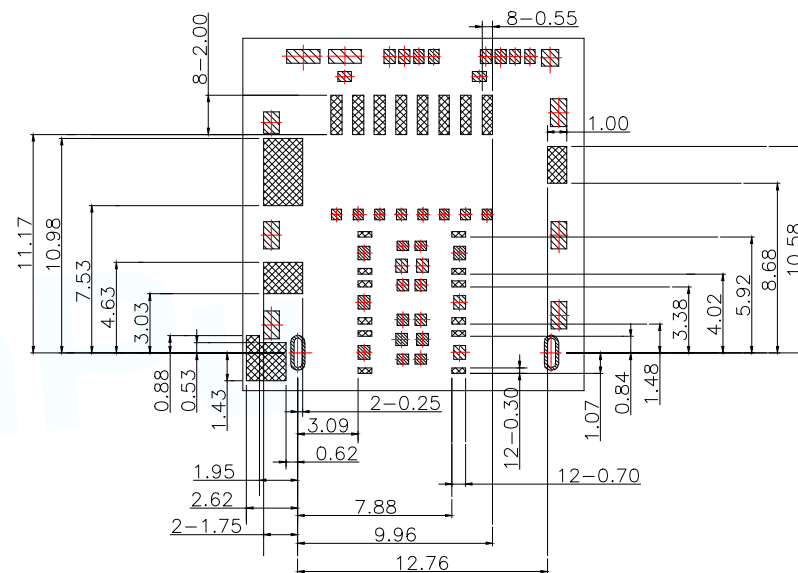
Year(1:2011;2:2012...)

Type(A:Au10u")

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE: 2.3H 3 IN 2卡座 FOR CUSTOMER	
DECIMALS:	ANGLES:	PAR	MCS-312-H230-C
X.:±0.25	X.':±2°	DWN	Lucas
X.X:±0.20	X.X':±1°	CHKD	Ethan
X.XX:±0.15		APVD	Jacob
CUSTOMER COPY		SCALE 1:1	UNIT:MM
		SIZE:A4	SHEET:2F4
			REV:A



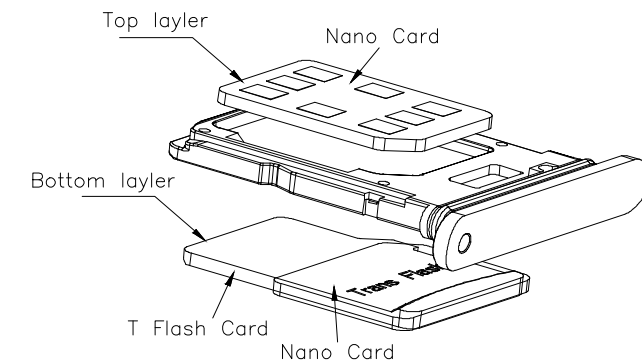
- Pad Area
○ Through Hole
PCB LAYOUT TOLERANCE:±0.05
METAL MASK THICKNESS:0.10MM
■ None Solder Pad Area
1:Touch area of contact tips,No electrical function and only for mechanical function
2:Don't brush Tin pasted on the area during SMT process.



MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd				
UNLESS OTHERWISE SPECIFIED TOLERANCES				TITLE: 2.3H 3 IN 2# FOR CUSTOMER		
				PAR	MCS-312-H230-C	
DECIMALS:	ANGLES:			DWN	Lucas	
X.:±0.25	X':±2°			CHKD	Ethan	
X.X:±0.20	X.X':±1°			APVD	Jacob	
X.XX:±0.15				SCALE1:1	UNIT:MM	
			CUSTOMER COPY	SIZE:A4	SHEET:3F4	REV:A

SD Block Pin Definition

SD Card	Pin	NAME
P1	A1	DAT2
P2	A2	CD/DAT3
P3	A3	CMD
P4	A4	VDD
P5	A5	CLK
P6	A6	VSS
P7	A7	DAT0
P8	A8	DAT1
	A9/A10	GROUND

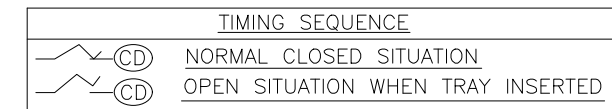
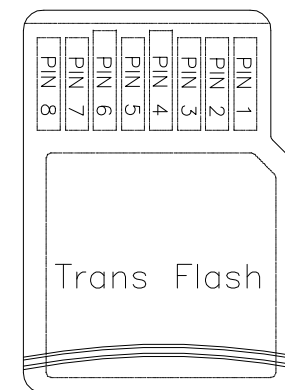
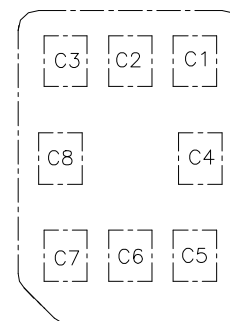
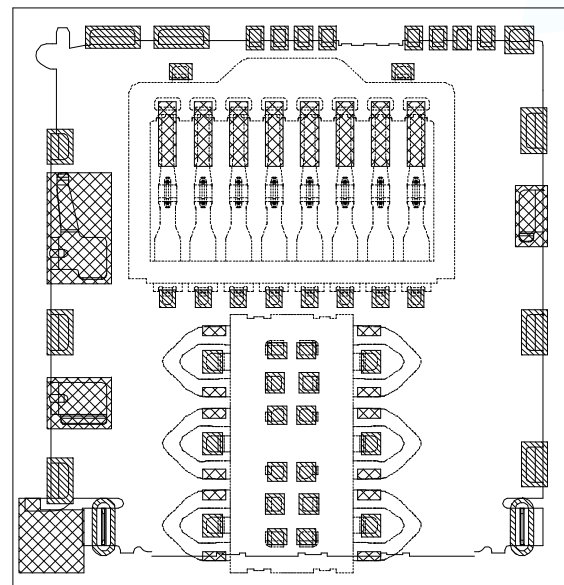
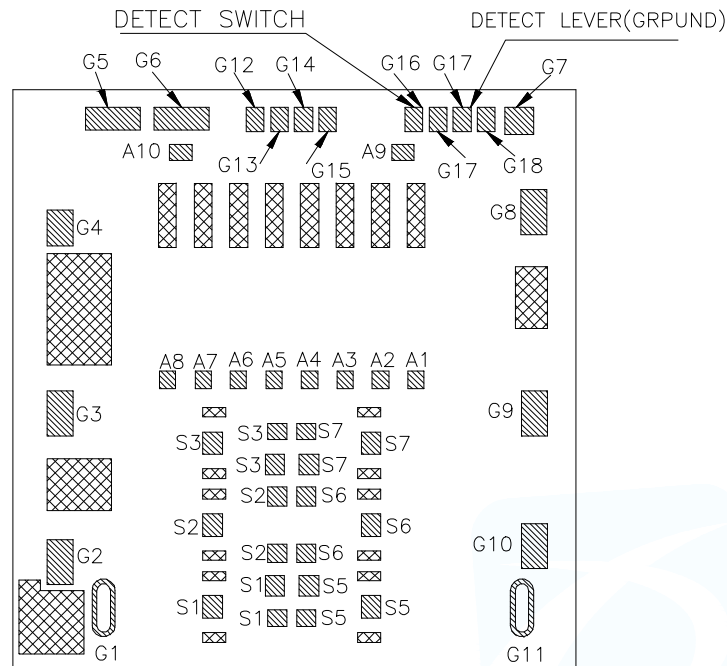


NANO Block Pin Definition

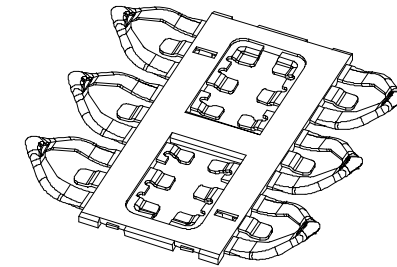
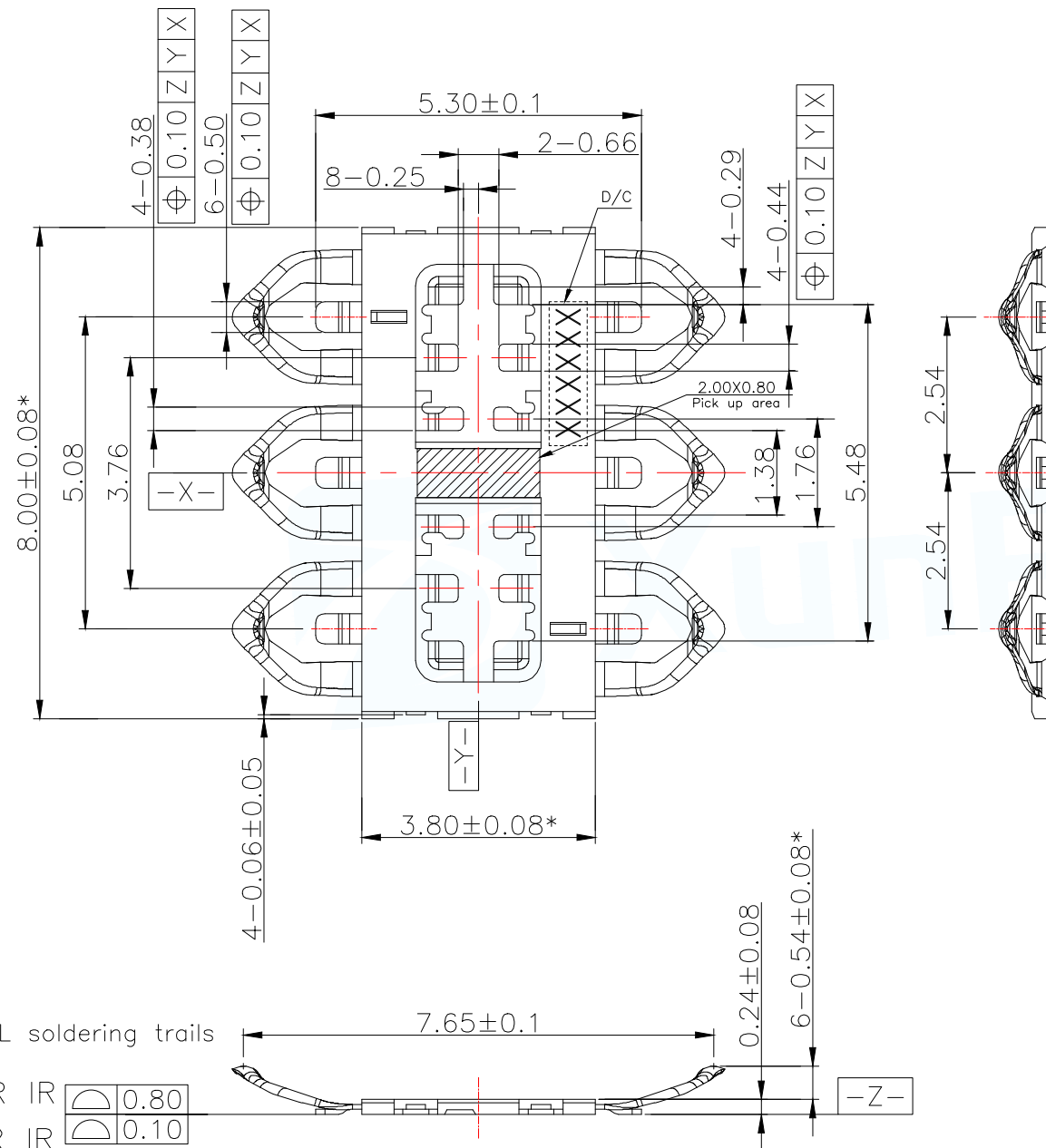
NANO Card	Pin	NAME
C1	S1	Vcc
C2	S2	RST
C3	S3	CLK
C5	S5	GND
C6	S6	Vpp
C7	S7	I/O

SHELL Block Pin Definition

NANO Card	Pin	NAME
C1	G17	Vcc
C2	G14	RST
C3	G12	CLK
C5	G18	GND
C6	G15	Vpp
C7	G13	I/O
G1~G11:GND PIN		
G19:DETECT LEVER(GROUND)G16:DETECT SWITCH		



MANUFACTURE DWG		东 莞 市 讯 普 电 子 科 技 有 限 公 司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE: 2.3H 3 IN 2卡 FOR CUSTOMER	
DECIMALS:	ANGLES:	PAR	MCS-312-H230-C
X.:±0.25	X'.:±2°	DWN	Lucas
X.X:±0.20	X.X':±1°	CHKD	Ethan
X.XX:±0.15		APVD	Jacob
CUSTOMER COPY		SCALE:1:1	UNIT:MM
		SIZE:A4	SHEET:4F4
			REV:A



3D VIEW

D/C ANNOTATION

LXXXXX

Class(A:Day Shift,B:Night shift)
Line(01,02,03..)
Date(1;2;3...A;B...)
Month(A:Jan;B:Feb...)
Year(1:2011; 2:2012...)

NOTES:

1.MATERIAL:

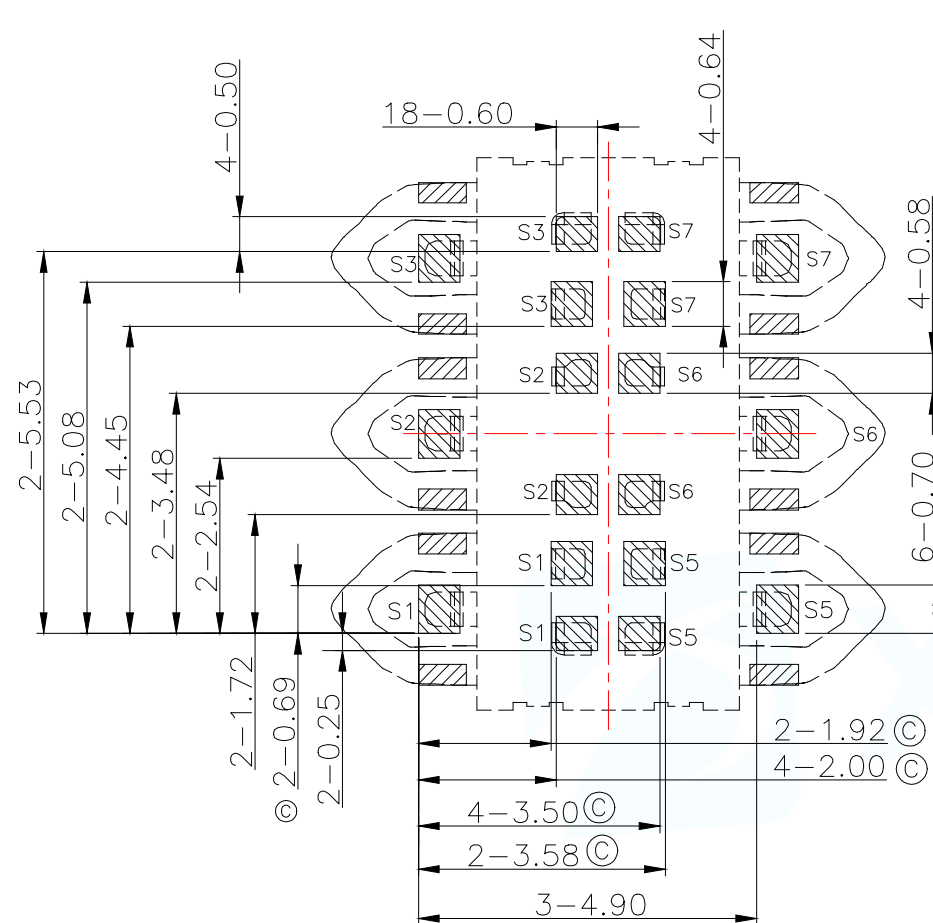
HOUSING:THERMOPLASTIC,UL 94V-0,BLACK;
CONTACT:COPPER ALLOY

2. PRODUCT SPECIFICATIONS;

VOLTAGE RATING; 10V
INSULATION RESISTANCE; 1 GOHM MIN
CONTACT RESISTANCE; 50mΩ Max. INITIAL;
AFTER TEST 75mΩ Max
OPERATION TEMPERATURE;-40° TO +85°
DURABILITY: 3000 CYCLES

3. DIMENSIONS WITH MARK "*"INDICATE THE CRITICAL DIMENSIONS

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			
DECIMALS:	ANGLES:	TITLE:0.24H 6PIN NANO SIM BLOCK FOR CUSTOMER	
X.:±0.25	X.':±2°	PAR	MCS-312-H230-A
X.X:±0.20	X.X':±1°	DWN	Lucas
X.XX:±0.15		CHKD	Ethan
		APVD	Jacob
		SCALE:1:1	UNIT:MM
		CUSTOMER COPY	SIZE:A4
			SHEET:1F2
			REV:A



Nano SIM Block PCB LAYOUT TOLERANCE: ± 0.05
STENCILS THICKNESS: 0.10

Nano SIM Block PCB LAYOUT(NO PATTERN) (TOLERANCE: ± 0.05)

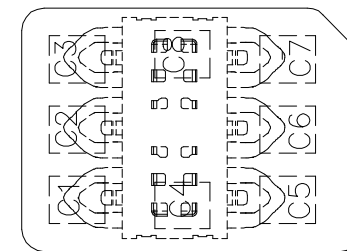
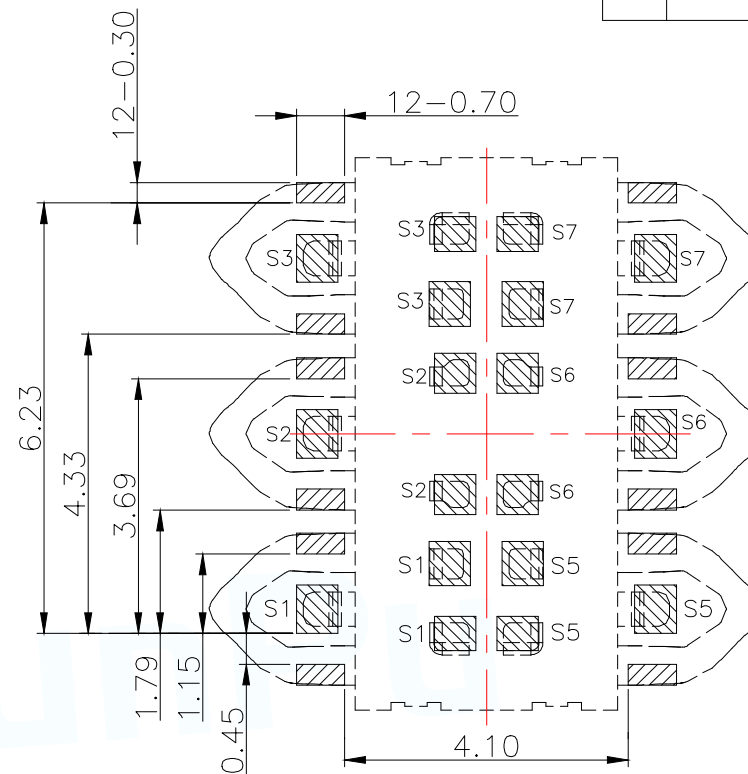
▨ Soldering pad

▨ None Solder Pad Area

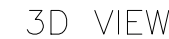
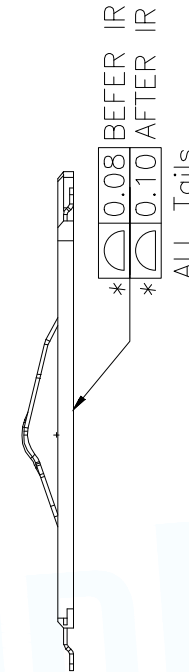
- 1.Touch area of contact tips,no electrical function and only for mechanical function
- 2.No first PCB-Layericut in the area

NANO Block Pin Definition

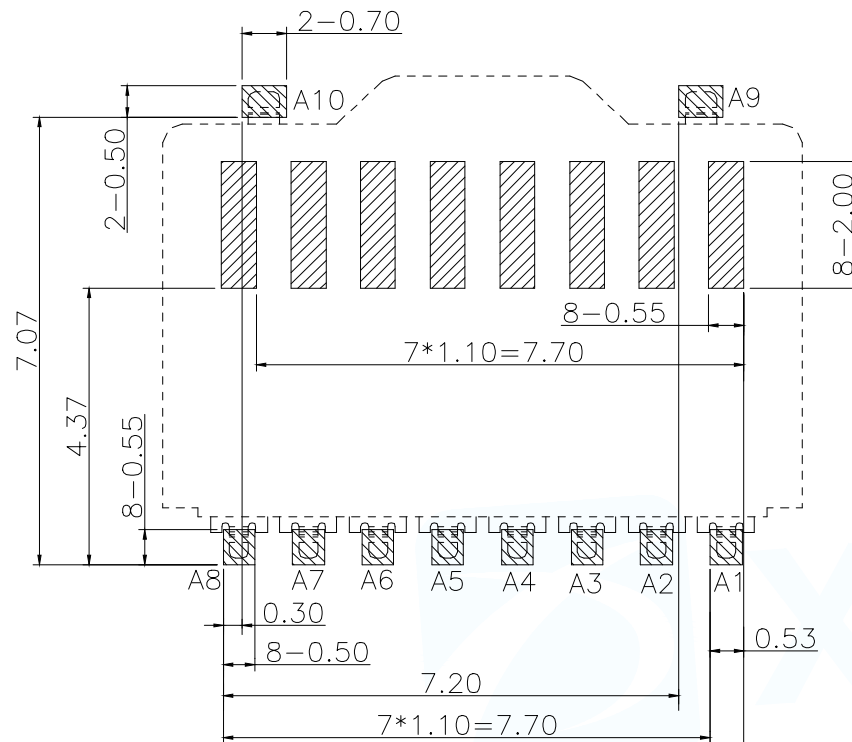
NANO Card	Pin	NAME
C1	S1	VCC
C2	S2	RST
C3	S3	CLK
C5	S5	GND
C6	S6	VPP
C7	S7	I/O



MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE:0.24H 6PIN NANO SIM BLOCK FOR CUSTOMER	
DECIMALS:	ANGLES:	PAR	MCS-312-H230-A
X.: ± 0.25	X': $\pm 2^\circ$	DWN	Lucas
X.X: ± 0.20	X.X': $\pm 1^\circ$	CHKD	Ethan
X.XX: ± 0.15		APVD	Jacob
CUSTOMER COPY		SCALE 1:1	UNIT:MM
		SIZE:A4	SHEET:2F2
			REV:A



REV:A

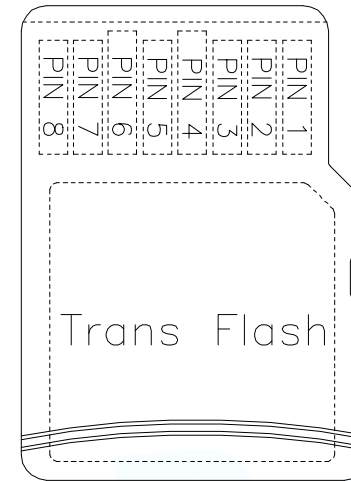


SD Block PCB LAYOUT TOLERANCE: ± 0.05
STENCILS THICKNESS: 0.10

▨ Soldering Pad Area

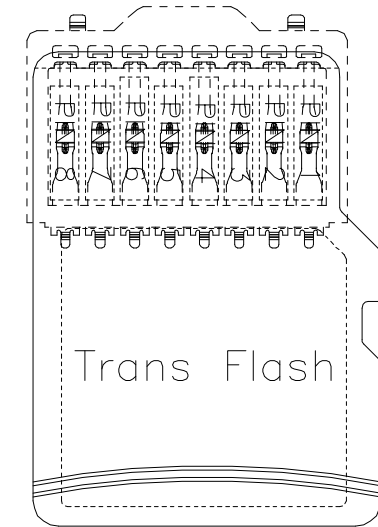
▨ None Solder Pad Area

- 1.Touch area of contact tips, no electrical function and only for mechanical function
- 2.No frist PCB-Layercircuit in the area



SD Block Pin Definition

SD Card	Pin	NAME
P1	A1	DAT2
P2	A2	CD/DAT3
P3	A3	CMD
P4	A4	VDD
P5	A5	CLK
P6	A6	VSS
P7	A7	DAT0
P8	A8	DAT1
	A9/A10	GROUND



MANUFACTURE DWG

UNLESS OTHERWISE
SPECIFIED TOLERANCES

DECIMALS:

X.: ± 0.25

X.X: ± 0.20

X.XX: ± 0.15

ANGLES:

X.: $\pm 2^\circ$

X.X: $\pm 1^\circ$



东莞市讯普电子科技有限公司
DongGuan XunPu Electronics Co.,Ltd



TITLE:0.24H 8PIN SD BLOCK
FOR CUSTOMER

PAR MCS-312-H230-B

DWN Lucas

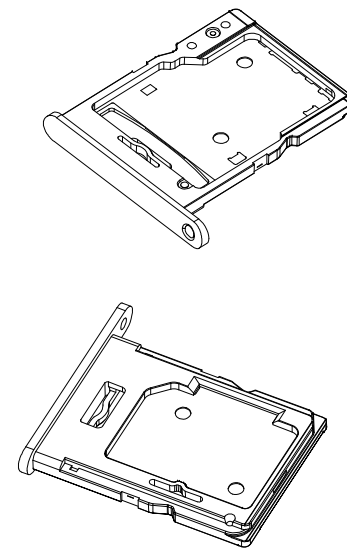
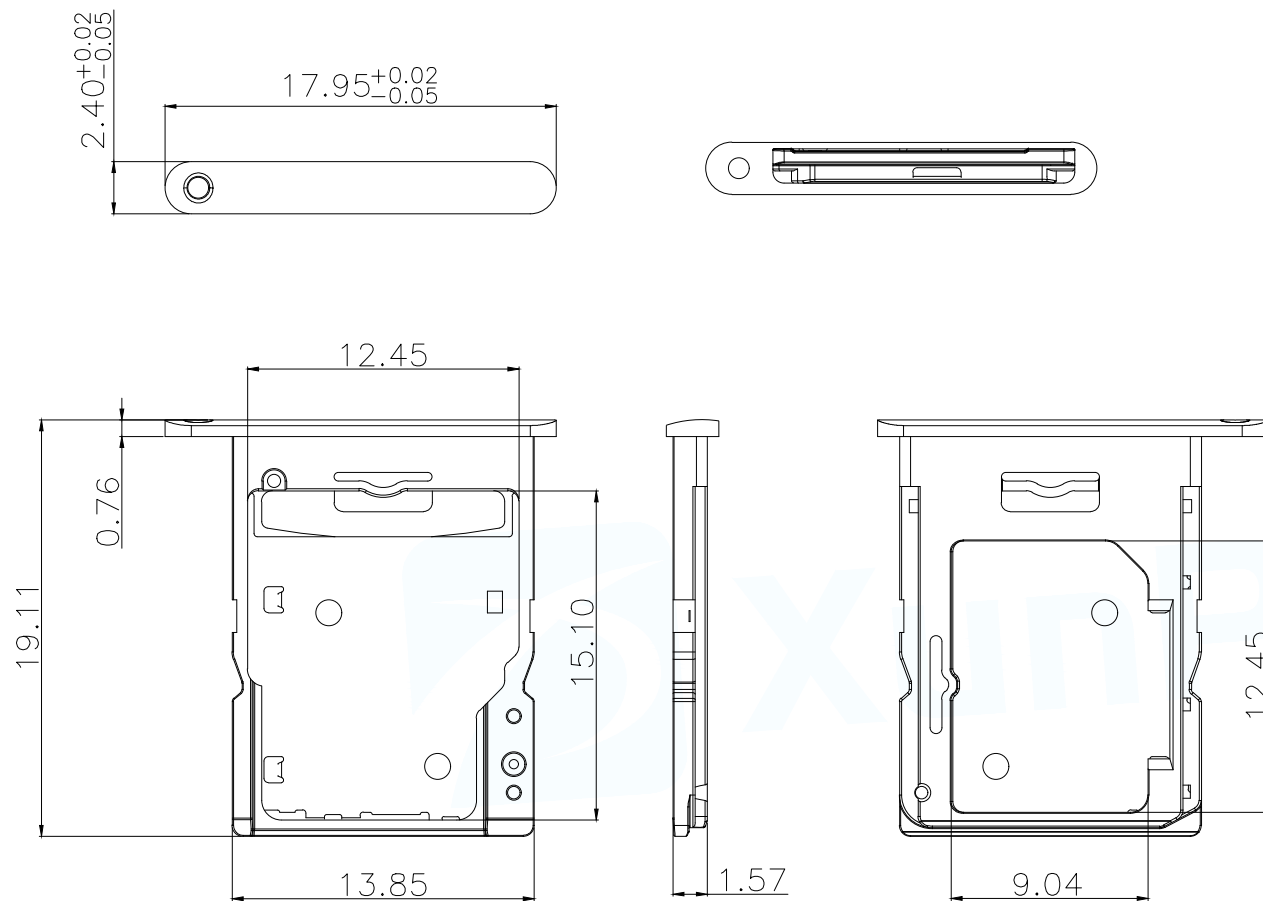
CHKD Ethan

APVD Jacob

SCALE1:1 UNIT:MM

SIZE:A4 SHEET:2F2 REV:A

CUSTOMER COPY



备注:

- 1.材质:塑胶PC+10% 纤,黑色; 五金SUS304,T0.10mm
- 2.毛边0.05mm 最大;
- 3.塑胶不可有缩水,变形,缺料,堵孔;
- 4.””重点巡检尺寸标识符号,””首检检验尺寸序号标识,
所有尺寸新模具、复制模、重大变更或维修时需全尺寸测量;
- 5.产品必须没有油,塑料残留物,脱模剂、污渍等
- 6.所用材质需符合ROHS要求;
- 7.模穴号(A.B.C....)

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
		TITLE: 2.3H 3 IN 2 柜	
		PAR	MCS-312-KT1
		DWN	Lucas
		CHKD	Ethan
DECIMALS:		APVD	
X.: $\pm$ 0.20		SCALE1:1	
X.X: $\pm$ 0.15		UNIT:MM	
X.XX: $\pm$ 0.10		SIZE:A4	
ANGLES:		SHEET:1F1	
X.: $\pm$ 2°		REV:A	
X.X': $\pm$ 1°			
CUSTOMER COPY			